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Part Number: **0737820200**
Status: **Active**
Overview: HDM® Backplane Connector System
Description: HDM® Board-to-Board Stacking Header, High Rise Vertical, SMC, Closed End Option, 72 Circuits

Documents:

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA LR19980
 UL E29179

General

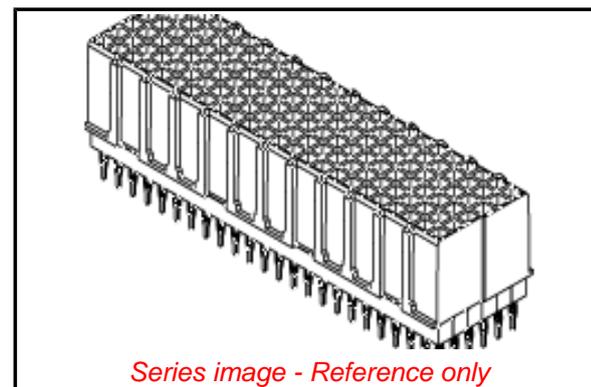
Product Family Backplane Connectors
 Series 73782
 Application Backplane, Mezzanine
 Component Type PCB Header
 Overview HDM® Backplane Connector System
 Product Name HDM®
 UPC 800754874175

Physical

Circuits (Loaded) 72
 Circuits (maximum) 72
 Color - Resin Black
 Durability (mating cycles max) 200
 First Mate / Last Break No
 Flammability 94V-0
 Guide to Mating Part No
 Keying to Mating Part None
 Material - Metal Phosphor Bronze
 Material - Plating Mating Gold
 Material - Plating Termination Tin-Lead
 Material - Resin High Temperature Thermoplastic
 Net Weight 12.108/g
 Number of Columns 12
 Number of Pairs Open Pin Field
 Number of Rows 6
 Orientation Vertical
 PC Tail Length 2.00mm
 PCB Locator No
 PCB Retention None
 PCB Thickness - Recommended 1.40mm
 Packaging Type Tube
 Pitch - Mating Interface 2.00mm
 Plating min - Mating 0.762µm
 Plating min - Termination 2.540µm
 Polarized to PCB No
 Stackable Yes
 Surface Mount Compatible (SMC) Yes
 Temperature Range - Operating -55°C to +105°C
 Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 1.0A



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Contains SVHC(2014 December 17): No

Halogen-Free

Status

Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
 Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS

ELV

Green Image

Not Relevant

Search Parts in this Series

73782 Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Data Rate	1.0 Gbps
Real Signals (per 25mm)	72
Voltage - Maximum	100V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	005
Lead-free Process Capability	WAVE
Max. Cycles at Max. Process Temperature	001
Process Temperature max. C	260

Material Info**Reference - Drawing Numbers**

Product Specification	PS-73780-999
Sales Drawing	SD-73782-001

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This document was generated on 07/02/2015

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